



Technical Data Sheet

DOWSIL™ EA-6247 Thermally Conductive Adhesive

DOWSIL™ EA-6247 Thermally Conductive Adhesive is a thixotropic thermally conductive adhesive with high tensile strength

Features & Benefits

- Thixotropic - increased flowability under shear/dispense
- Heat Cure
- Outstanding thermal conductivity values
- High tensile strength
- No added solvents
- No mixing of separate components required
- Rapid, versatile cure processing controlled by temperature
- Able to flow, fill or self-leveling after dispensing
- Heat flow away from circuitry components can increase reliability

Composition

- 1-part, gray
- Polydimethylsiloxane adhesive

Application Methods

- Automated or manual needle dispense

Applications

- Attaching ceramic circuitry
- Base plate attach
- Heat sink attach
- Lid and housing bonding

Typical Properties

Specification Writers: These values are not intended for use in preparing specifications.

Property	Unit	Result
Viscosity	cP	61700
	mPa-sec	61700
	Pa-sec	61.7
Thixotropy	NA	3.7
Heat Cure Time @ 100°C	minutes	90
Heat Cure Time @ 125°C	minutes	30
Heat Cure Time @ 150°C	minutes	20

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Typical Properties (Cont.)

Property	Unit	Result
Specific Gravity (Cured)		2.7
Durometer Shore A		92
Unprimed Adhesion - Lap Shear to Aluminum	psi MPa N/cm ²	670 4.6 461
Thermal Conductivity	btu/hr ft degF W/mK	3.097 1.79
Linear CTE (by TMA)	ppm/°C	125
Shelf Life at 5°C	months	6

Description

The heat-cure, thermally conductive adhesives produce no by-products in the cure process, allowing their use in deep section and complete confinement. These adhesives will develop good, primerless adhesion to a variety of common substrates including metals, ceramics, epoxy laminate boards, reactive materials and filled plastics. Long-term, reliable protection of sensitive circuits and components is important in many of today's delicate and demanding PCB system assembly applications. With the increase in processing power and the trend toward smaller, more compact PCB system assemblies, the need for thermal management is growing. Thermally conductive silicones function as heat transfer media, durable dielectric insulation, barriers against environmental contaminants and as stress-relieving shock and vibration absorbers over a wide temperature and humidity range. In addition to sustaining their physical and electrical properties over a broad range of operating conditions, silicones are resistant to ozone and ultraviolet degradation and have good chemical stability. Good heat transfer is dependent on a good interface between the heat producing device and the heat transfer media. Silicones have a low surface tension that enables them to wet most surfaces, which can lower the thermal contact resistance between the substrate and the material.

Substrate Testing

To ensure maximum bond strength for adhesives on a particular substrate, 100 percent cohesive failure of the adhesive in a lap shear or similar adhesive strength test is needed. This ensures compatibility of the adhesive with the substrate being considered. Also, this test can be used to determine minimum cure time or to detect the presence of surface contaminants such as mold release agents, oils, greases and oxide films.

Processing/Curing

Addition-cure adhesives should be cured at 100°C (212°F) or above. The cure rate is rapidly accelerated with heat (see heat-cure times in Typical Properties table). Thin sections of less than 20 mils may be cured in 15 minutes at 150°C (30°F). For thicker sections, a pre-cure at 70°C (158°F) may be necessary to reduce voids in the elastomer. Length of pre-cure will depend on section thickness and confinement of adhesive. It is recommended that 30 minutes at 70°C (158°F) be used as a starting point for determining necessary pre-cure time. Addition-curing materials contain all the ingredients needed for cure with no by-products from the cure mechanism. Deep-section or confined cures are possible. Cure progresses evenly throughout the material. These adhesives generally have long working times.

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Adhesion	Dow silicone adhesives are specially formulated to provide unprimed adhesion to many reactive metals, ceramics and glass, as well as to selected laminates, resins and plastics. However, good adhesion cannot be expected on non-reactive metal substrates or non-reactive plastic surfaces such as Teflon®, polyethylene or polypropylene. Special surface treatments such as chemical etching or plasma treatment can sometimes provide a reactive surface and promote adhesion to these types of substrates. Dow primers can be used to increase the chemical activity on difficult substrates. For best results, the primer should be applied in a very thin, uniform coating and then wiped off after application. After application, primers should be thoroughly cured prior to application of the silicone elastomer. Poor adhesion can be experienced on plastic or rubber substrates that are highly plasticized, since the mobile plasticizers act as release agents. Small-scale laboratory evaluation of all substrates is recommended before production trials are made. In general, increasing the cure temperature and/or cure time will improve the ultimate adhesion.
Useful Temperature Ranges	For most uses, silicone adhesives should be operational over a temperature range of -45 to 200°C (-49 to 392°F) for long periods of time. However, at both the low and high temperature ends of the spectrum, behavior of the materials and performance in particular applications can become more complex and require additional considerations. For low-temperature performance, thermal cycling to conditions such as -55°C (-67°F) may be possible for most products, but performance should be verified for your parts or assemblies. Factors that may influence performance are configuration and stress sensitivity of components, cooling rates and hold times, and prior temperature history. At the high-temperature end, the durability of the cured silicones is time and temperature dependent. As expected, the higher the temperature, the shorter the time the material will remain useable.
Solvent Exposure	Although highly filled silicones such as those discussed in this data sheet are generally more resistant to solvent or fuel exposure, standard silicones are intended only to survive splash or intermittent exposures. Testing should be done to confirm performance of the adhesives in the application and under the specified environmental conditions.
Usable Life And Storage	Shelf life is indicated by the "Use By" date found on the product label. For best results, Dow thermally conductive materials should be stored at or below the maximum specified storage temperature. Special precautions must be taken to prevent moisture from contacting these materials. Containers should be kept tightly closed and head or air space minimized. Partially filled containers should be purged with dry air or other gases, such as nitrogen. Any special storage and handling instructions will be printed on the product containers.
Handling Precautions	PRODUCT SAFETY INFORMATION REQUIRED FOR SAFE USE IS NOT INCLUDED IN THIS DOCUMENT. BEFORE HANDLING, READ PRODUCT AND SAFETY DATA SHEETS AND CONTAINER LABELS FOR SAFE USE, PHYSICAL AND HEALTH HAZARD INFORMATION. THE SAFETY DATA SHEET IS AVAILABLE ON THE DOW WEBSITE AT WWW.CONSUMER.DOW.COM , OR FROM YOUR DOW SALES APPLICATION ENGINEER, OR DISTRIBUTOR, OR BY CALLING DOW CUSTOMER SERVICE.

Health And Environmental Information

To support customers in their product safety needs, Dow has an extensive Product Stewardship organization and a team of product safety and regulatory compliance specialists available in each area.

For further information, please see our website, www.consumer.dow.com or consult your local Dow representative.

Limitations

This product is neither tested nor represented as suitable for medical or pharmaceutical uses.

How Can We Help You Today?

Tell us about your performance, design, and manufacturing challenges. Let us put our silicon-based materials expertise, application knowledge, and processing experience to work for you.

For more information about our materials and capabilities, visit www.consumer.dow.com.

To discuss how we could work together to meet your specific needs, go to www.consumer.dow.com for a contact close to your location. Dow has customer service teams, science and technology centers, application support teams, sales offices, and manufacturing sites around the globe.

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